

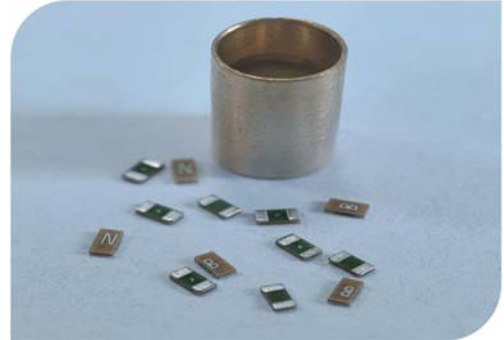
Ultra-Thin Fuse | 0.06x0.03"

0603TD-L Series

Time Delay series Thin Film Chip Fuse

Features

- Low DCR
- High inrush current withstanding capability
- High reliability
- Fiberglass enforced epoxy fuse body
- Copper termination with nickel and tin plating layer
- Halogen free, RoHS compliance & lead-free



Application

- Panel
- HDD
- Toy
- IoT
- Battery pack
- Finger print
- Smart lock
- Notebook

Electrical Characteristics

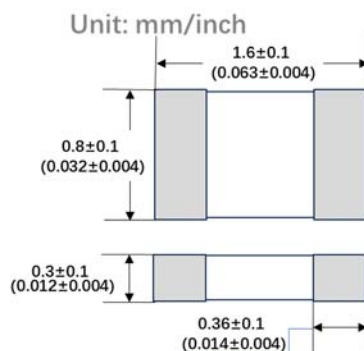
% of Current Rating	Opening Time
100%	4hours min.
200%	5second max.
300%	0.2second max.

Specifications

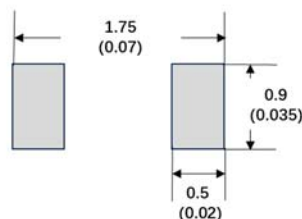
Part No.	Current Rating(A)	Voltage Rating (Vdc)	Interrupting Rating	Typical Cold DCR (Ω)	Typical I^2t (A^2Sec)*	Marking
0603TD-R750-L	0.75	35	35A @35V	0.11	0.02	H

*Typical I^2t : i.e. melting I^2t at 0.001s of current rating

Dimension



Pad layout



Packaging

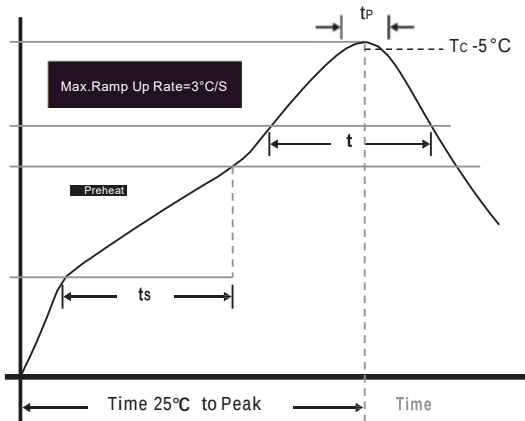
- Quantity: 5, 000pcs
- 8mm wide tape on 178mm (7 inch) diameter reel -specification EIA Standard 481

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Soldering Parameters



Wave Soldering: 260°C, 10 seconds max.

Infrared Reflow: 260°C, 30 seconds max.

IR Reflow Profile

Preheat Heat
Temperature min (T_{min}) 150°C
Temperature max (T_{max}) 200°C
Time (T_{min} to T_{max}) (ts) 60 - 120 seconds

Average ramp-up rate (T_{max} to T_p) 3°C/second max.

Liquidous temperature (T_L) 217 °C
Time at liquidous (t_L) 60 - 150 seconds

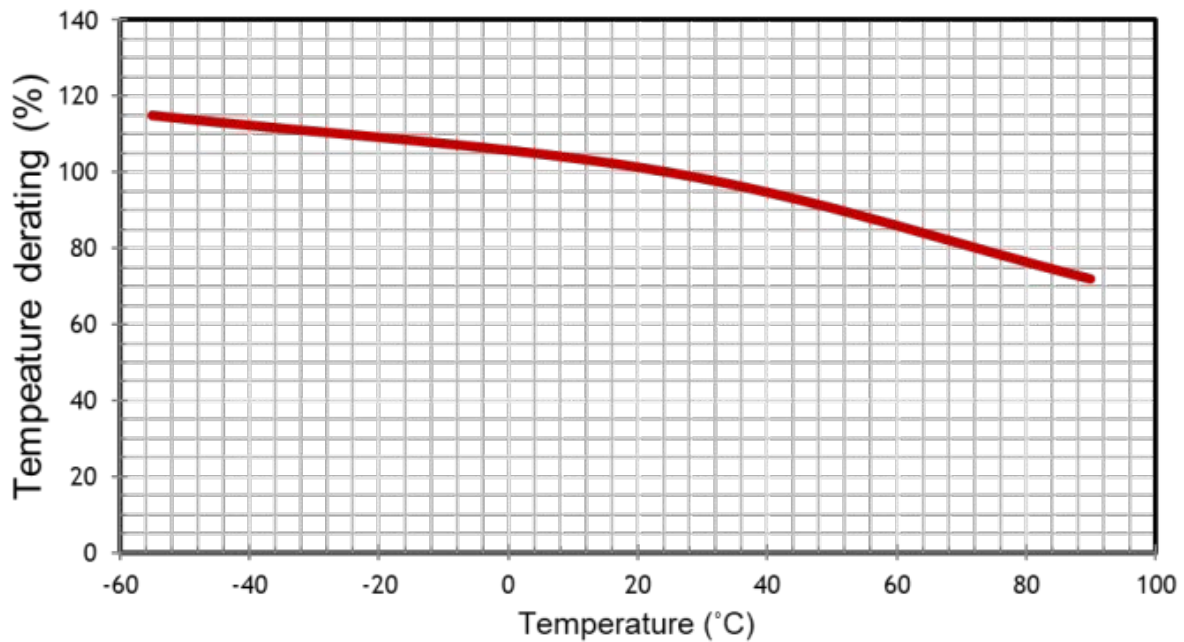
Peak temperature (T_p) 260°C

Time within 5°C of actual peak Temperature (tp) 30 seconds

Average ramp-down rate (T_p to T_{max}) 6°C/second max.

Time 25 °C to peak temperature 8 minutes max.

Temperature Effect on Current Rating



- Normal ambient temperature: 23+/-3°C
- Operating temperature: -55 ~ 105°C

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Average Time-Current curve

